

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Wolfgang Hetzel et al. Examiner: Unknown  
Serial No.: 10/577,173 Group Art Unit: Unknown  
  
Filed: April 26, 2006 Docket: I441.141.101 (formerly  
I431.156.101/FIN546PCT/US)  
  
Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING  
COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND  
METHOD FOR PRODUCING SAME

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**SECOND STATUS INQUIRY**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

An application for the above-identified patent application was filed on April 26, 2006.

We have **not received any type of communication** at all.

Kindly inform Applicant as to the status of this application.

Any inquiries may be directed to Applicant's attorney, Mark L. Gleason, at (612) 767-2503.

Respectfully submitted,  
Wolfgang Hetzel et al.,  
By their attorneys,

Dated: 06/16/2009  
MLG:cjs

/Mark L. Gleason/  
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